

MECHANICAL CASE OUTLINE

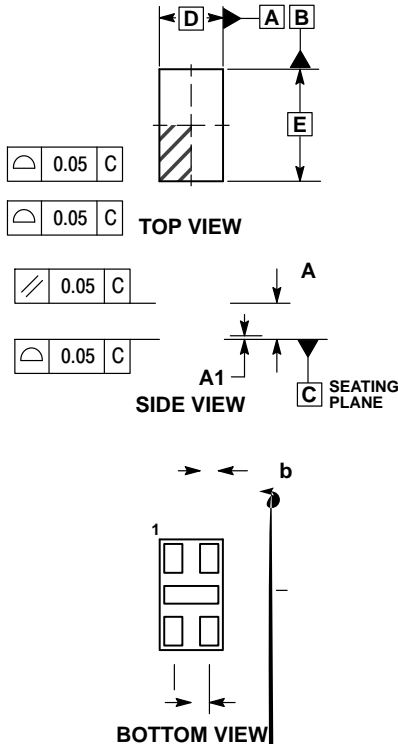
PACKAGE DIMENSIONS



SCALE 8:1

X3DFN4 0.525x0.925, 0.3P
 CASE 714AA
 ISSUE B

DATE 08 DEC 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

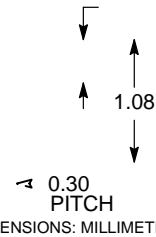
MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.32
A1	0.00	0.05
b	0.12	0.18
E	0.925 BSC	
e	0.30 BSC	

GENERIC MARKING DIAGRAM*

X = Specific Device Code
 M = Date Code
 6649XIN ON REFERENCE 7

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.